

**RISC-V** 

# **Board Support Package Module Using Software Integration System**

## Summary

The Renesas board support package module (r\_bsp) forms the foundation of any project that uses Software Integration System. The r\_bsp is easily configurable and provides all the code needed to get the MCU and the board from reset to the main() function. This document describes r\_bsp conventions and explains how to use it, configure it, and create a BSP for your own board.

## **Device on Which Operation Confirmed**

RISC-V

## **Supported Compilers**

• LLVM C/C++ Compiler for Renesas RISC-V

For details of the confirmed operation of each compiler, refer to 7.1, Confirmed Operating Environment.

1.	Overview	4
1.1	Terminology	4
1.2	File Structure	5
2.	Functionality	7
2.1	MCU Information	7
2.2	Initial Settings	8
2.3	Global Interrupts	10
2.4	Clock Settings	10
2.5	Stack Area	10
2.6	ID Code	10
2.7	Option-Setting Memory	10
2.8	CPU Functionality	11
2.9	Disabling Startup	11
2.9.	1 Settings to Disable Startup	11
3.	Configuration	12
3.1	Choosing a Platform	12
3.2	Platform Configuration	12
3.2.	.1 MCU Product Part Number Information	12
3.2.	2 Data Flash Access Restriction	12
3.2.	3 Clock Settings	13
3.2.	4 Option-Setting Memory	15
3.2.	.5 Security ID Codes for On-Chip Debugging	15
3.2.	6 Startup Disable	15
3.2.	7 Smart Configurator	16
3.2.	8 API Functions disable Usage	16
3.2.	9 Parameter check Usage	17
3.2.	10 Callback Function at Warm Start	17
4.	API Information	18
4.1	Hardware Requirements	18
4.2	Hardware Resource Requirements	18
4.3	Software Requirements	18
4.4	Supported Toolchains	18
4.5	Interrupt Vectors Used	18
4.6	Header Files	18
4.7	Integer Types	18
4.8	API Typedef	19
4.8.	1 Clock Resource	19
4.8.	2 Clock Divider	19
4.8.	3 Unit of Software Delay	19

4.8.4 Re	gister Write Protection Unit	20
4.9 Ret	ırn Values	21
4.9.1 En	or Codes	21
4.10 Cod	e Size	22
4.11 "for,	" and "while," Statements	23
5. API	- unctions	24
5.1 Ove	rview	24
5.2 R_E	SP_StartClock()	25
5.3 R_E	SP_StopClock()	26
5.4 R_E	SP_GetIClkFreqHz()	27
5.5 R_E	SP_ChangeICLKClockSetting ()	28
5.6 R_E	SP_SoftwareDelay()	30
5.7 R_E	SSP_DelayCycle ()	32
5.8 R_E	SSP_GetVersion ()	33
5.9 R_E	SSP_RegisterProtectEnable ()	34
5.10 R_E	SP_RegisterProtectDisable ()	35
6. proje	ct setup	36
6.1 Hov	to add the BSP	36
6.2 Add	ing the BSP to a Project in e² studio	37
6.2.1 Ad	ding the BSP Using Smart Configurator in e <sup>2</sup> studio	37
7. Appe	endix	40
7.1 Con	firmed Operating Environment	40
Revision	History	/11

#### 1. Overview

Before running a user application there are a series of operations that must be performed to get the MCU set up properly. These operations, and their number, will vary depending on the MCU being used. Common examples include: setting up stack(s), initializing memory, configuring the CPU and peripheral hardware clock, and setting up port pins. The steps described in this document must to be followed in order to configure the above items. The r\_bsp is provided in order to make configuration easier.

The r\_bsp provides all the elements needed to get the MCU from reset to the start of the user application's main() function. The r\_bsp also provides common functionality that is needed by many applications. Examples of this include functions to start and stop the clocks and to get the frequency of the CPU and peripheral hardware clock.

The necessary steps after a reset are the same for every application, but this does not mean that the settings will be the same. For example, stack sizes and the clocks used will vary depending on the application. The r\_bsp configuration options are contained in the config header file for easy access.

## 1.1 Terminology

Term	Description
Platform	The user's development board. Used interchangeably with "board."
BSP	Abbreviation of "board support package."

R01AN7177EJ0100 Rev.1.00 Mar.18.24



### 1.2 File Structure

The r\_bsp file structure is shown below in Figure 1.1. The r\_bsp folder contains three folders and two files.

The *doc* folder contains r\_bsp documentation.

The board folder contains the generic folders.

There is a *generic* folder for each supported MCU.

Figure 1.2 shows the contents of the *generic* folder.

The *mcu* folder contains one folder for each supported MCU. The *mcu* folder also contains the *all* folder, which contains source code common to all MCUs supported by the r bsp.

The *platform.h* file allows you to choose your current development platform. It is used to select all the header files from the *board* and *mcu* folders required for your project. This is discussed in more detail in later sections.

The *readme.txt* file provides a summary of information about the r\_bsp.

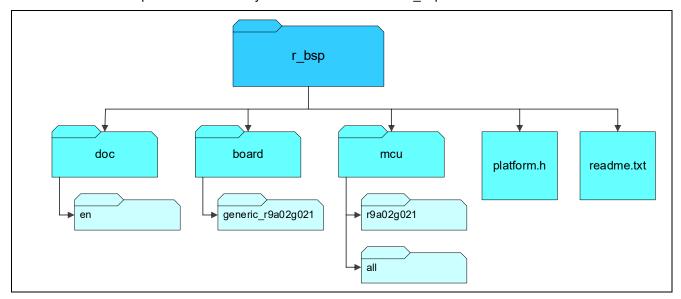


Figure 1.1 r\_bsp File Structure

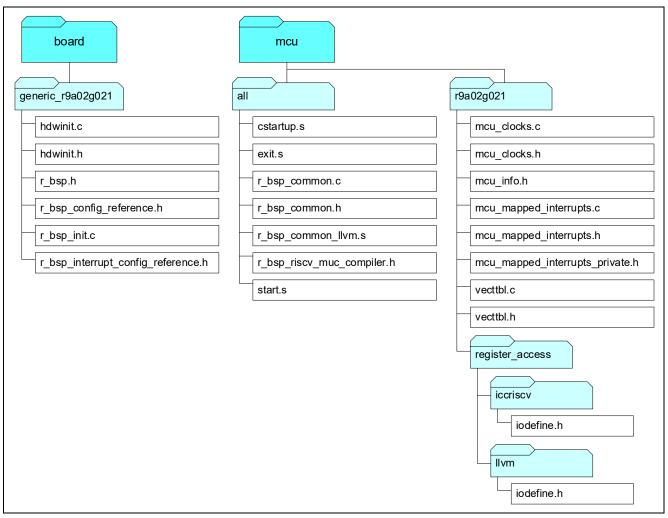


Figure 1.2 Structure of Generic Folder

## 2. Functionality

This section describes in detail the functionality provided by the r\_bsp.

## 2.1 MCU Information

One of the main benefits of the r\_bsp is that it lets you define the global system settings only once, in a single place in the project, and those settings are then shared throughout. This information is defined in the r\_bsp and can then be used by the SIS modules and user code. SIS modules use this information to automatically configure their code to match your system configuration. If the r\_bsp did not provide this information, you would have to specify system information to each SIS module separately.

Configuring the r\_bsp is discussed in Section 3. The r\_bsp uses this configuration information to set macro definitions in *mcu\_info.h*. An example of an MCU-specific macro in *mcu\_info.h* is shown below.

Definition	Description
BSP_MCU_FAMILY_RISCV_MCU	Which MCU Family this MCU belongs to.
BSP_MCU_SERIES_ASSPEASY	Which MCU Series this MCU belongs to.
BSP_MCU_GROUP_G021	Which MCU group this MCU belongs to.
BSP_LOCO_HZ	Each of these macros corresponds to one of the MCU's clocks.
BSP_SOSC_HZ	Each macro defines the corresponding clock's frequency in
BSP_MOCO_HZ	hertz (Hz). For example, BSP_LOCO_HZ defines the LOCO
	frequency in Hz, and BSP_SUB_CLOCK_HZ defines the
	subsystem clock frequency in Hz.

R01AN7177EJ0100 Rev.1.00 Mar.18.24



## 2.2 Initial Settings

The PowerON\_Reset function is set as the reset vector when using the LLVM compiler. The PowerON\_Reset\_PC function (the startup function) performs various types of initialization processing to get the MCU ready to use the user application. The flowcharts below show startup function operations and CPU and peripheral hardware clock settings.

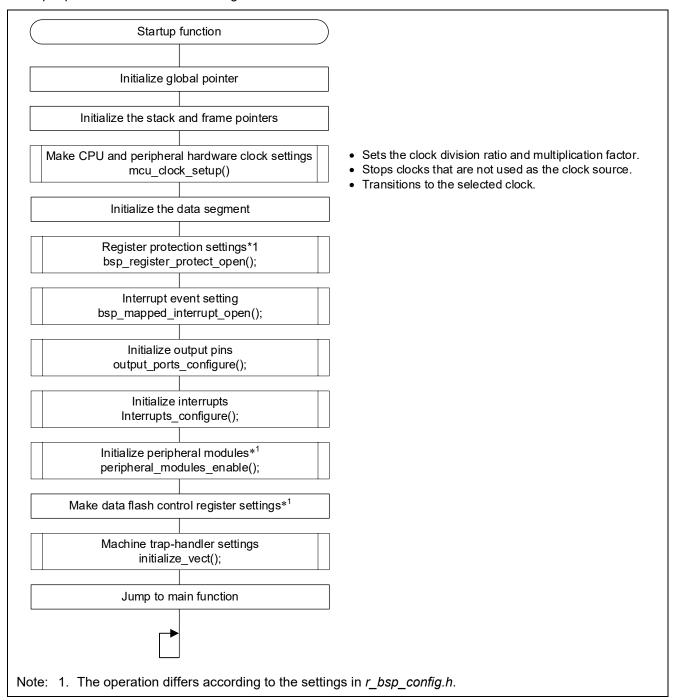


Figure 2.1 Flowchart of Startup Function

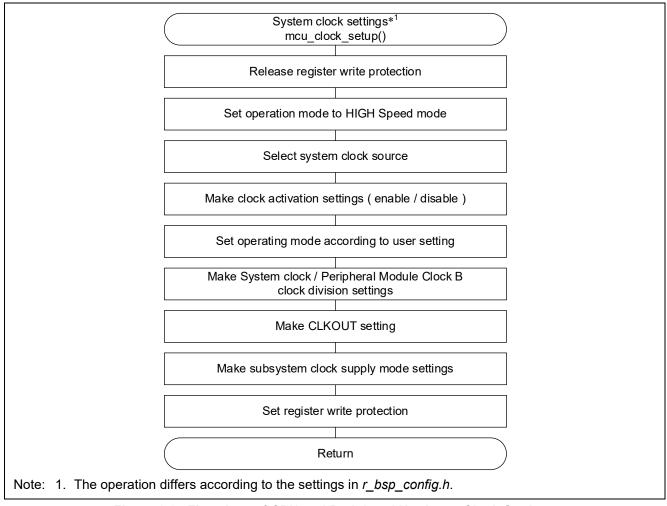


Figure 2.2 Flowchart of CPU and Peripheral Hardware Clock Settings

#### 2.3 Global Interrupts

Interrupts are disabled after a reset. Enable interrupts as needed. Use the BSP CFG INTERRUPT SETTING DISABLE function to specifies the interrupt vector for each interrupt event. For details, refer to 5.1, Overview.

#### 2.4 **Clock Settings**

CPU and peripheral hardware clock settings are made during r bsp initialization. Clocks are configured based upon the user's settings in the r bsp config.h file (see  $3.\overline{2.5}$ ). Clock settings are applied before the C runtime environment is initialized. When a clock is selected, the code in the r bsp implements the required delays to allow the selected clock to stabilize.

#### 2.5 Stack Area

The stacks are configured and initialized by the startup function after a reset.

#### ID Code 2.6

RISC-V MCUs have an ID code stored in ROM that protects the MCU's memory from being read through a debugger, or in serial boot mode, in an attempt to extract the firmware from the device. ID code resides in the on-chip debug security ID setting memory. The value of the security ID values (macro) are specified in r bsp config.h, its value is depended on setting of user in Smart Configurator. The ID code is set in vecttble.c using macros that is defined in r\_bsp\_config.h. For details of ID code options, refer to the Option-Setting Memory and chapters is mentioned on -chip debug mode in your MCU's hardware manual.

#### 2.7 **Option-Setting Memory**

The Option-Setting Memory are located in the flash memory of RISC-V MCUs. The Option-Setting Memory are referenced automatically after power-on or a reset, and the specified function settings are applied. Option-Setting Memory can be used to specify settings for the watchdog timer or voltage detection circuit, for example. Option-Setting Memory setting values (macro) are specified in r bsp config.h, its value is depended on setting of user in Smart Configurator. Option-Setting Memory is set in vecttble.c using macros that is defined in r bsp config.h.

RENESAS

## 2.8 CPU Functionality

API functions are provided for making settings related to CPU functionality such as enabling and disabling interrupts. Refer to Section 5 for details.

## 2.9 Disabling Startup

To disable startup, manually delete the startup assembler code. The names of the files containing the startup assembler code for each environment are as follows:

LLVM compiler: start.s

Additionally, you will need to add your own startup code.

## 2.9.1 Settings to Disable Startup

Make settings as described below to disable BSP startup processing.

### (1) Configuration File Settings

Specify your own startup processing in  $r\_bsp\_config.h$ . Some BSP API functions and peripheral SIS modules reference the contents of  $r\_bsp\_config.h$ . Note that some SIS modules may not function correctly if there are discrepancies between the details of the startup processing you created and the contents of  $r\_bsp\_config.h$ .

The BSP information referenced by the peripheral SIS modules is generated based on  $r\_bsp\_config.h$ , so it is necessary to ensure that the details of the startup processing you created and the contents of  $r\_bsp\_config.h$  match.

Figure 2.3 illustrates configuration file settings.

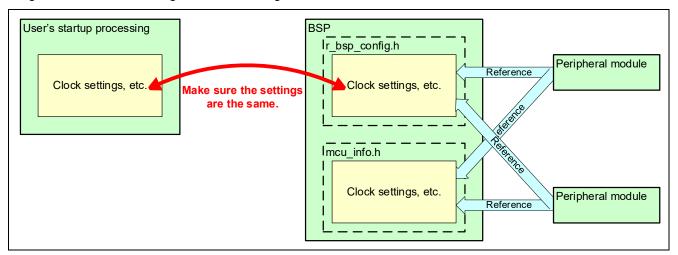


Figure 2.3 Configuration File Settings

## 3. Configuration

Two header files are used to configure the r\_bsp. One is used to choose the platform, and the other to configure the chosen platform.

## 3.1 Choosing a Platform

The r\_bsp provides board support packages for a variety of MCUs. Choosing the platform to be used is accomplished by modifying the *platform.h* file located in the *r\_bsp* folder.

## 3.2 Platform Configuration

After selecting a platform, you must configure it. The file *r\_bsp\_config.h* contains the platform settings. Each platform has a configuration file called *r\_bsp\_config\_reference.h*, which is located in the platform's *board* folder.

The contents of each *r\_bsp\_config.h* file differs according to the MCU associated with it, but many of the options are the same. The following sections provide details on these configuration options. Note that each macro starts with the common prefix "BSP\_CFG\_," which makes them easy to search for and identify.

When using Smart Configurator, the configuration options can be set on the software component configuration screen. Setting values are automatically reflected in *r\_bsp\_config.h* when adding modules to a user project.

#### 3.2.1 MCU Product Part Number Information

The MCU's product part number information makes it possible to provide a variety of information about the MCU along with the r\_bsp. Information related to the MCU's product part number is defined at the beginning of the configuration file. All of these macros start with "BSP\_CFG\_MCU\_PART." Some MCUs have more product part number–related information than others, but the standard definitions are listed below.

**Table 3.1 Product Part Number Definitions** 

Definition	Value	Description
BSP_CFG_MCU_PART_ROM_TYPE	See comments above	Defines the device type.
BSP_CFG_MCU_PART_PACKAGE	#define in r_bsp_config.h.	Defines the package type.

#### 3.2.2 Data Flash Access Restriction

RISC-V MCUs are provided with functionality to enable or disable access to the data flash. After a reset the r\_bsp makes data flash access settings using the data flash access restriction functionality configuration macros in r\_bsp\_config.h.

Table 3.2 Data Flash Access Restriction Definitions

Definition	Value	Description
BSP_CFG_DATA_FLASH_ACCESS_ENABLE	0 : Access to the data flash memory area is disabled.	Data flash memory area access control
	1 : Access to the data flash memory area is enabled.	Data flash control register(DFLCTL) DFLEN

RENESAS

## 3.2.3 Clock Settings

The available clocks vary among RISC-V MCUs, but the same basic concepts apply to all. After a reset the r\_bsp initializes the MCU clocks using the clock configuration macros in *r\_bsp\_config.h*.

**Table 3.3 Clock Setting Definitions** 

Definition	Value	Description
BSP_CFG_ICLK_DIV	0 : x 1/1	System Clock Division Control
	1 : x 1/2	Register (SCKDIVCR)
	2 : x 1/4	System Clock (ICLK) Select
	3 : x 1/8	(ICK[2:0])
	4 : x 1/16	
	5 : x 1/32	
	6 : x 1/64	
BSP_CFG_PCLKB_DIV	0 : x 1/1	System Clock Division Control
	1 : x 1/2	Register (SCKDIVCR)
	2 : x 1/4	Peripheral Module Clock B (PCLKB)
	3 : x 1/8	Select (PCKB[2:0])
	4 : x 1/16	
	5 : x 1/32	
	6 : x 1/64	
BSP_CFG_CLOCK_SOURCE_SEL	0 : HOCO	System Clock Source Control
	1 : MOCO	Register (SCKSCR)
	2:LOCO	Clock Source Select (CKSEL[2:0])
	3 : External clock input	
	(EXTAL)	
	4 : Sub-clock oscillator	
DOD OF CENTON OPERATION	(SOSC) 0 : Stop	External Clark Imput Control Denister
BSP_CFG_EXTCLK_OPERATION	1 : Operate	External Clock Input Control Register (MOSCCR)
BSP_CFG_SUBCLK_OPERATION	0 : Stop	Sub-Clock Oscillator Control Register
BOI_OI O_OODOLIK_OI LIKKIION	1 : Operate	(SOSCCR).
BSP CFG SUBCLK MODE	0 : Normal Mode	Sub-Clock Oscillator Mode Control
BOI _OI O_OOBOLK_MODE	1 : Low Power Mode 1	Register (SOMCR)
	2 : Low Power Mode 2	
	3 : Low Power Mode 3	
BSP CFG SUBCLK MARGIN	0 : Normal Current	Sub-Clock Oscillator Margin Check
	1 : Lower Margin check	Register (SOMRG)
	2 : Upper Margin check	,
BSP CFG LOCO OPERATION	0 : Stop	Low-Speed On-Chip Oscillator
	1 : Operate	Control Register (LOCOCR)
BSP_CFG_HOCO_OPERATION	0 : Stop	High-Speed On-Chip Oscillator
	1 : Operate	Control Register (HOCOCR)
BSP_CFG_MOCO_OPERATION	0 : Stop	Middle-Speed On-Chip Oscillator
	1 : Operate	Control Register (MOCOCR)
BSP_CFG_CLKOUT_SEL	0 : HOCO	Clock Out Control Register (CKOCR)
	1: MOCO	Clock Out Source Select
	2:LOCO	(CKOSEL[2:0])
	3 : External clock input	
	(EXTAL)	
	4 : Sub-clock oscillator	
	(SOSC)	

Definition	Value	Description
BSP_CFG_CLKOUT_DIV	0 : x 1/1	Clock Out Control Register (CKOCR)
	1 : x 1/2	Clock Output Frequency Division
	2:x 1/4	Ratio (CKODIV[2:0])
	3 : x 1/8	
	4 : x 1/16	
	5 : x 1/32	
	6 : x 1/64	
	7 : x 1/128	
BSP_CFG_CLKOUT_ENABLE	0 : Disable	Clock Out Control Register (CKOCR)
	1 : Enable	Clock Out Enable (CKOEN)
BSP_CFG_SUBCLK_SEL	0 : Subsystem clock	Subsystem Clock Supply Mode
	(SOSC)	Control Register (OSMCR)
	1 : Low-speed on-chip	Selection of the operating clock for
	oscillator clock (LOCO)	the realtime clock, 32-bit interval
		timer,serial interfaces UARTA0 and
		UARTA1, remote control signal
DOD OFO EVTAL LIZ	[	receiver (WUTMMCK0)
BSP_CFG_EXTAL_HZ	Frequency (Hz)	Input clock frequency in Hz (EXTAL).
BSP_CFG_EXTCLK_INPUT_JTAG_HZ	Frequency (Hz)	Input clock frequency in Hz (JTAG).
BSP_CFG_OPERATION_MODE	0: High-speed mode	Operation Power Mode Select
	1: Middle-speed mode	(OPCCR register and SOPCCR
	2: Subosc-speed mode	register).
	3: Low-speed mode	

## 3.2.4 Option-Setting Memory

You can select the behavior after a reset by setting Option-Setting Memory. For example, you can specify settings for the watchdog timer and voltage detection circuit.

Option-Setting Memory setting values (macro) are specified in r\_bsp\_config.h, its value is depended on setting of user in Smart Configurator. Option-Setting Memory is set in vecttble.c using macros that is defined in r\_bsp\_config.h.

**Table 3.4 Option-Setting Memory Definitions** 

Definition	Value	Description
BSP_CFG_OFS0_REG_VALUE	Option-Setting Memory value	Specifies the setting value of the
BSP_CFG_OFS1_REG_VALUE		corresponding Option-Setting
		Memory.

#### 3.2.5 Security ID Codes for On-Chip Debugging

You can protect against third parties reading the contents memory by setting Security ID Codes for On-Chip Debugging.

The Security ID Codes for On-Chip Debugging setting values(macro) are defined r bsp\_config.h, its value is depended on setting of user in Smart Configurator. The Security ID Codes for On-Chip Debugging is set in vecttble.c using macros that is defined in r\_bsp\_config.h.

Table 3.5 Security ID Codes for On-Chip Debugging Definitions

Definition	Value	Description
BSP_CFG_OCD_SERIAL_ID_VALUE_0		Specifies the setting value of the
BSP_CFG_OCD_SERIAL_ID_VALUE_1 BSP_CFG_OCD_SERIAL_ID_VALUE_2	Debugging / Serial programing value	corresponding Security ID Codes for On-Chip Debugging or serial
BSP_CFG_OCD_SERIAL_ID_VALUE_3		programming.

## 3.2.6 Startup Disable

**Table 3.6 Startup Disable Definitions** 

Definition	Value	Description
BSP_CFG_STARTUP_DISABLE	0 : Enable BSP startup	Start up select.
	program.	
	1 : Disable BSP startup	
	program.(e.g. Using user	
	startup program.)	

RENESAS Mar.18.24

# 3.2.7 Smart Configurator

**Table 3.7 Smart Configurator Definitions** 

Definition	Value	Description
BSP_CFG_CONFIGURATOR_SE	0 = Smart Configurator not	Defines whether or not Smart
LECT	used	Configurator is used in the current
	1 = Smart Configurator used	project. When
	_	BSP_CFG_CONFIGURATOR_SELE
		CT = 1, the Smart Configurator
		initialization function is called.
BSP_CFG_CONFIGURATOR_VE	See comments above	Defines the version of Smart
RSION	#define in r_bsp_config.h.	Configurator you are using.

## 3.2.8 API Functions disable Usage

Table 3.8 API Functions disable Usage Definitions

Definition	Value	Description
BSP_CFG_CLOCK_OPERATION	0 = API Functions enable	Defines whether API
_API_FUNCTIONS_DISABLE	1 = API Functions disable	Functions(R_BSP_StartClock,
		R_BSP_StopClock) is disabled.
		When
		BSP_CFG_CLOCK_OPERATION_A PI FUNCTIONS DISABLE = 1,
		cannot use API Functions, but can
		reduce the memory size.
BSP CFG CHANGE CLOCK S		Defines whether API
ETTING_API_FUNCTIONS_DISA		Functions(R_BSP_ChangeClockSetti
BLE		ng) is disabled.
		When
		BSP_CFG_CHANGE_CLOCK_SETT
		ING_API_FUNCTIONS_DISABLE = 1, cannot use API Functions, but can
		reduce the memory size.
BSP CFG REGISTER WRITE		Defines whether API
PROTECTION DISABLE		Functions(R_BSP_RegisterProtectDis
_		able, R_BSP_RegisterProtectEnable)
		is disabled.
		When
		BSP_CFG_REGISTER_WRITE_PRO
		TECTION_DISABLE = 1, cannot use API Functions, but can reduce the
		memory size.
BSP CFG INTERRUPT SETTIN		Defines whether API
G_DISABLE		Functions(bsp_mapped_interrupt_op
_		en) is disabled.
		When
		BSP_CFG_INTERRUPT_SETTING_
		DISABLE = 1, cannot use API
		Functions, but can reduce the memory size.
		memory size.

## 3.2.9 Parameter check Usage

# Table 3.9 Parameter check Usage Definitions

Definition	Value	Description
BSP_CFG_PARAM_CHECKING_ ENABLE	0 = Parameter check is invalid	Defines whether parameter check is enabled.
	1 = Parameter check is valid	Returns an error for incorrect setting when switching System clock source.

## 3.2.10 Callback Function at Warm Start

**Table 3.10 Warm Start Callback Function Definitions** 

Definition	Value	Description
BSP_CFG_USER_WARM_STAR T_CALLBACK_PRE_INITC_ENA BLED	0 = User function is not called before C runtime environment is initialized 1 = User function is called before C runtime environment is initialized	Defines whether or not a user function is called before the C runtime environment is initialized.
BSP_CFG_USER_WARM_STAR T_PRE_C_FUNCTION	Function called before C runtime environment is initialized	Defines the user function called before the C runtime environment is initialized.
BSP_CFG_USER_WARM_STAR T_CALLBACK_POST_INITC_EN ABLED	0 = User function is not called after C runtime environment is initialized 1 = User function is called after C runtime environment is initialized	Defines whether or not a user function is called after the C runtime environment is initialized.
BSP_CFG_USER_WARM_STAR T_POST_C_FUNCTION	Function called after C runtime environment is initialized	Defines the user function called after the C runtime environment is initialized.

#### 4. API Information

The driver API conforms to Renesas API naming conventions.

## 4.1 Hardware Requirements

Not applicable.

## 4.2 Hardware Resource Requirements

Not applicable.

## 4.3 Software Requirements

None

## 4.4 Supported Toolchains

The operation of this SIS module has been confirmed with the toolchains listed in 7.1, Confirmed Operating Environment.

## 4.5 Interrupt Vectors Used

This SIS module does not use interrupt vectors.

### 4.6 Header Files

All API calls are included by incorporating the file *platform.h*, which is supplied with the driver's project code.

## 4.7 Integer Types

This project uses ANSI C99 "Exact width integer types" in order to make the code clearer and more portable. These types are defined in *stdint.h*.

RENESAS

## 4.8 API Typedef

#### 4.8.1 Clock Resource

This typedef defines commands that can be used with the R\_BSP\_StartClock(), R\_BSP\_StopClock() and R\_BSP\_ChangelCLKClockSetting() functions.

Available resources vary from device to device.

See the user's manual or r\_bsp\_common.h.

#### 4.8.2 Clock Divider

This typedef defines commands that can be used with the R\_BSP\_ChangelCLKClockSetting() functions.

Available setting of divider varies from device to device.

See the user's manual or *r\_bsp\_common.h*.

```
typedef enum
{
    DIV_BY_1,
    DIV_BY_2,
    DIV_BY_4,
    DIV_BY_8,
    DIV_BY_16,
    DIV_BY_32,
    DIV_BY_32,
    DIV_BY_64,
    DIV_BY_128,
} e_clock_div_t;
```

#### 4.8.3 Unit of Software Delay

This typedef defines units which can be used with the R BSP SortwareDelay function.

#### 4.8.4 Register Write Protection Unit

This typedef defines the types of registers that can be used by the R\_BSP\_RegisterProtectEnable() and R\_BSP\_RegisterProtectDisable() functions.typedef enum.

```
typedef enum
   /* PRC0
     Enables writing to the registers related to the clock generation circuit:
SCKDIVCR, SCKSCR, HOCOCR, MOCOCR, CKOCR, HOCOUTCR, LOCOCR, LPOPT, OSMCR, MOSCCR,
SOSCCR, SOMCR, SOMRG, MEMWAIT, LOCOUTCR, MOCOUTCR */
  BSP REG PROTECT CGC = 0,
   /* PRC1
     Enables writing to the registers related to low power mode: SBYCR, OPCCR,
SYOCDCR, PSMCR, SNZCR, SNZEDCRO, SNZEDCRI, SNZREQCRO, SOPCCR, SYOCDCR, PSMCR */
  BSP REG PROTECT LPM,
   /* PRC3
      Enables writing to the registers related to the LVD: LVD1CR1, LVD1SR, LVD2CR1,
LVD2SR, LVCMPCR, LVDLVLR, LVD1CR0, LVD2CR0 */
  BSP REG PROTECT LVD,
   /* SRAM.SRAMPRCR
     Enables writing to the PARIOAD register. */
  BSP REG PROTECT SRAM,
   /* SRAM.ECCPRCR
     Enables writing to the ECCMODE, ECC1STSEN, and ECCOAD registers. */
   BSP_REG_PROTECT_ECC,
   /* SRAM.ECCPRCR2
      Enables writing to the ECCETST register. */
   BSP REG PROTECT ECC2,
   /* PWPR
     Enable write to the PmnPFS register */
   BSP_REG_PROTECT_PMNPFS,
   /* This entry is used for getting the number of enum items. This must be the last
entry. DO NOT REMOVE THIS ENTRY! */
  BSP_REG_PROTECT_TOTAL_ITEMS
} e bsp reg protect t;
```

## 4.9 Return Values

### 4.9.1 Error Codes

This typedef defines the error codes that can be returned by the  $R_BSP_StartClock()$ ,  $R_BSP_StartClock()$ ,

```
typedef enum
{
   BSP_OK,
   BSP_ARG_ERROR,
   BSP_ERROR1,
   BSP_ERROR2,
   BSP_ERROR3
} e_bsp_err_t;
```

Member	Description
BSP_OK	Success.
BSP_ARG_ERROR	An invalid argument was input.
BSP_ERROR1	The specified clock is not oscillating or stopping.
	The error occurrence conditions differ depending on the function.
BSP_ERROR2	When switching between clock resources, a clock resource that is not
	oscillating may have been switched to.
BSP_ERROR3	An unsupported state transition was specified. Refer to the user's manual.

#### 4.10 Code Size

The sizes od ROM, RAM and maximum stack usage associated with this module are listed below.

The ROM (code and constants) and RAM (global data) sizes are determined by the build-time configuration options described in Section 3, Configuration.

The values in the table below are confirmed under the following conditions:

Module revision: r\_bsp v1.00

Compiler version: LLVM for RISC-V (17.0.0.202310)

Configuration options: Default settings

ROM, RAM, and Stack Code Sizes (R9A02G021)					
	API	Clock			
Compiler	function *1	setting *2	ROM	RAM	STACK
LLVM compiler *3	Disable	Default	2450	0	T.B.D
		All enable	2646	0	T.B.D
	Enable	Default	4924	0	T.B.D
		All enable	5140	0	T.B.D

#### Note 1:

Use macro definition BSP\_CFG\_XXXX\_API\_FUNCTIONS\_DISABLE in *r\_bsp\_config.h* to enable / disable. The above measurement results are the values when all macro definitions are enabled or disabled.

#### Note 2:

The default is the initial value of Smart Configurator.

Only valid for high-speed on-chip oscillator clock.

#### Note 3:

If measure the stack size using the LLVM compiler, add "-fstack-size-section" to the Compiler options.

R01AN7177EJ0100 Rev.1.00 Mar.18.24



## 4.11 "for," and "while," Statements

This module uses "for" statements (loop processing) for wait processing to allow register values to take effect, for example. These instances of loop processing are indicated by the comment keyword "WAIT\_LOOP." Therefore, if you wish to incorporate fail-safe processing into the instances of loop processing, you can locate them in the source code by searching for the keyword "WAIT\_LOOP."

A code sample is shown below:

```
for statement:
    /* WAIT_LOOP */
    for (w_count = 0U; w_count < 2U; w_count++)
    {
        R_BSP_NOP();
}</pre>
```

# 5. API Functions

## 5.1 Overview

The module uses the following functions:

Function	Description
R_BSP_StartClock	Starts oscillation of the specified clock.
R_BSP_StopClock	Stops oscillation of the specified clock.
R_BSP_GetIClkFreqHz	Returns the system clock frequency.
R_BSP_SoftwareDelay	Delays the specified duration.
R_BSP_ChangeICLKClockSetting	Switch CPU/peripheral hardware clock (ICLK) clock source.
R_BSP_GetVersion	Get the current version of the r_bsp.
R_BSP_RegisterProtectEnable	Enables write protection for selected registers.
R_BSP_RegisterProtectDisable	Disables write protection for selected registers.
R_BSP_DelayCycle	Delay the specified duration in CPU cycle.

## 5.2 R\_BSP\_StartClock()

This function starts oscillation of the specified clock.

#### **Format**

```
e bsp err t R BSP StartClock(e clock mode t mode);
```

#### **Parameters**

mode

Specifies the clock on which oscillation will start (see 4.9.1).

#### **Return Values**

```
BSP_OK /* The specified clock is started. */
BSP_ARG_ERROR /* The specified clock is incorrect. */
```

## **Properties**

Prototyped in *r\_bsp\_common.h*.

## **Description**

This function starts oscillation of the specified clock.

To use the oscillated clock as the system clock, the CSKSCR register must be changed by separately calling "5.5 R\_BSP\_ChangelCLKClockSetting".

#### **Example**

```
e_bsp_err_t err;

/* Disable register protection */
R_BSP_RegisterProtectDisable(BSP_REG_PROTECT_CGC);

/* Start High-speed on-chip oscillator */
err = R_BSP_StartClock(HOCO);

if (err != BSP_OK)
{
    /* NG processing */
}

/* Enable register protection */
R_BSP_RegisterProtectEnable(BSP_REG_PROTECT_CGC);
```

#### **Special Notes:**

This function is only available if the macro definition (BSP CFG CLOCK OPERATION API FUNCTIONS DISABLE) is set to 0.

## 5.3 R\_BSP\_StopClock()

This function stops oscillation of the specified clock. However, operation cannot be guaranteed if oscillation of a clock used as the CPU and peripheral hardware clock is stopped.

#### **Format**

```
e_bsp_err_t R_BSP_StopClock(e_clock_mode_t mode);
```

#### **Parameters**

mode

Specifies the clock on which oscillation will stop (see 4.9.1).

#### **Return Values**

```
BSP_OK /* The specified clock is stopped. */

BSP_ERROR2 /* The specified clock can not be stopped because it is ICLK clock's source. */

BSP_ARG_ERROR /* The specified clock is incorrect. */
```

## **Properties**

Prototyped in *r* bsp common.h.

#### **Description**

This function stops oscillation of the specified clock.

#### **Example**

```
e_bsp_err_t err;

/* Disable register protection */
R_BSP_RegisterProtectDisable(BSP_REG_PROTECT_CGC);

/* Stop High-speed on-chip oscillator */
err = R_BSP_StopClock(HOCO);

if (err != BSP_OK)
{
    /* NG processing */
}

/* Enable register protection */
R_BSP_RegisterProtectEnable(BSP_REG_PROTECT_CGC);
```

#### **Special Notes:**

This function is only available if the macro definition (BSP\_CFG\_CLOCK\_OPERATION\_API\_FUNCTIONS\_DISABLE) is set to 0.

## 5.4 R\_BSP\_GetIClkFreqHz()

This function returns the system clock frequency.

#### **Format**

```
uint32 t R BSP GetIClkFreqHz(void);
```

#### **Parameters**

None

#### **Return Values**

System clock frequency specified by the r\_bsp

## **Properties**

Prototyped in *r\_bsp\_common.h*.

### **Description**

This function returns the system clock frequency. For example, when the system clock is set to 120 MHz in  $r\_bsp\_config\_h$  and the  $r\_bsp$  has completed to specify the clock setting, then even if the user changed the system clock frequency to 60 MHz, the return value is '60000000'.

#### **Example**

```
uint32_t fclk_freq;
fclk freq = R BSP GetFclkFreqHz();
```

## 5.5 R\_BSP\_ChangelCLKClockSetting ()

This function changes the ICLK clock value by changing its clock source and division. This function is also used to change PCLKB clock value.

#### **Format**

```
e_bsp_err_t R_BSP_ChangeICLKClockSetting(e_clock_mode_t mode, e_clock_div_t
iclkdiv, e clock div t pclkdiv);
```

#### **Parameters**

mode

Specifies clock resources supplied to the system clock (see 4.9.1)

iclkdiv, pclkdiv

The division ratio for the clock source is specified by the following constants defined in the e\_clock\_div\_t structure.

DIV\_BY\_1: 1/1.DIV\_BY\_2: 1/2DIV\_BY\_4: 1/4

DIV\_BY\_8: 1/8
DIV\_BY\_16: 1/16
DIV\_BY\_32: 1/32
DIV\_BY\_64: 1/64

• DIV\_BY\_128: 1/128

#### **Return Values**

BSP\_OK when changing setting is done.

BSP\_ERROR1 The specified clock is not oscillating.

BSP\_ERROR3 An unsupported state transition was specified. Refer to the user's manual.

BSP\_ARG\_ERROR An invalid argument was input.

#### **Properties**

Prototyped in *r\_bsp\_common.h*.

#### Description

This function changes the clock source of the system clock to the specified clock and division value.



## **Example**

```
e_bsp_err_t err;

/* Disable register protection */
R_BSP_RegisterProtectDisable(BSP_REG_PROTECT_CGC);

/* Start clock operation(HOCO) with division */
    err = R_BSP_ChangeICLKClockSetting(HOCO, DIV_BY_2, DIV_BY_8);

    if (err != BSP_OK)
    {
        /* NG processing */
     }

/* Enable register protection */
R_BSP_RegisterProtectEnable(BSP_REG_PROTECT_CGC);
```

#### **Special Note:**

This function is available only when the macro definition (BSP\_CFG\_CHANGE\_CLOCK\_SETTING\_API\_FUNCTIONS\_DISABLE) is set to 0.

## 5.6 R\_BSP\_SoftwareDelay()

Delay the specified duration in units and return.

#### **Format**

```
e_bsp_err_t R_BSP_SoftwareDelay(uint32_t delay, e_bsp_delay_units_t units);
```

#### **Parameters**

delay

The number of 'units' to delay.

units

The 'base' for the units specified. See Section 4.8.3.

## **Return Values**

BSP\_OK /\* BSP\_OK if delay executed. \*/

BSP ERROR1 /\* BSP ERROR1 if delay/units combination resulted in overflow/underflow. \*/

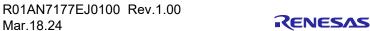
#### **Properties**

Prototyped in *r\_bsp\_common.h*.

### **Description**

This is function that may be called for all MCU targets to implement a specific wait time.

The actual delay time will take overhead into account. The overhead changes under the influence of the compiler, operating frequency and ROM cache. When the operating frequency is low, or the specified duration in units of microsecond level, please note that the error becomes large.



## Example

```
e_bsp_err_t ret;

/* Delay 5 seconds before returning */
ret = R_BSP_SoftwareDelay(5, BSP_DELAY_SECS);

if (BSP_OK != ret)
{
    /* NG processing */
}

/* Delay 5 milliseconds before returning */
ret = R_BSP_SoftwareDelay(5, BSP_DELAY_MILLISECS);

if (BSP_OK != ret)
{
    /* NG processing */
}

/* Delay 50 microseconds before returning */
ret = R_BSP_SoftwareDelay(50, BSP_DELAY_MICROSECS);

if (BSP_OK != ret)
{
    /* NG processing */
}
```

## 5.7 R\_BSP\_DelayCycle ()

This function is an assembly language wait loop.

### **Format**

void R\_BSP\_DelayCycle(uint32\_t wait\_cycle);

### **Parameters**

wait\_cycle

The number of CPU cycle to delay.

### **Return Values**

None

#### **Properties**

Prototype declared in r\_bsp\_common.h.

### **Description**

This is function that may be called for all MCU targets to implement a specific wait time.

#### Example

R\_BSP\_DelayCycle(100);

## 5.8 R\_BSP\_GetVersion ()

This function gets the version of the BSP.

### **Format**

```
uint32_t R_BSP_GetVersion (void);
```

#### **Parameters**

None

### **Return Values**

32-bit integer representing the BSP version (((uint32\_t)R\_BSP\_VERSION\_MAJOR) << 16) | ((uint32\_t)R\_BSP\_VERSION\_MINOR)

## **Properties**

Prototype declared in *r\_bsp\_common.h*.

## **Description**

This function can get the compiler's current BSP version information as an integer value.

### Example

uint32\_t ver\_num; ver num = R BSP GetVersion();

## 5.9 R\_BSP\_RegisterProtectEnable ()

This function sets write protection to the specified register.

#### **Format**

```
void R_BSP_RegisterProtectEnable (bsp_reg_protect_t regs_to_protect);
```

#### **Parameters**

regs\_to\_protect

Register type to set write protection (see 4.8.4)

#### **Return Values**

None

### **Properties**

Prototype declared in *r\_bsp\_common.h*.

### **Description**

This function allows the user to set write protection for a specific register. It is limited to specific registers that can be specified. (See 4.8.4)

#### **Example**

```
bsp_reg_protect_t regs_to_protect = BSP_REG_PROTECT_ECC;

/* set BSP_REG_PROTECT_ECC registers (ECCMODE, ECC1STSEN, and ECCOAD) to disable writing */
    R_BSP_RegisterProtectEnable (regs_to_protect);
```

## 5.10 R\_BSP\_RegisterProtectDisable ()

This function disables write protection for selected registers.

#### **Format**

```
void R_BSP_RegisterProtectEnable (bsp_reg_protect_t regs_to_protect);
```

#### **Parameters**

regs\_to\_unprotect

Register type to release write protection.

#### **Return Values**

None

### **Properties**

Prototype declared in *r\_bsp\_common.h*.

### **Description**

This function can remove write protection to a specific register. Only certain registers can be specified.

Please check bsp\_reg\_protect\_t (enum structure) in *r\_bsp\_common.h* to see which registers can be specified.

## **Example**

```
bsp_reg_protect_t regs_to_unprotect = BSP_REG_PROTECT_ECC;

/* set BSP_REG_PROTECT_ECC registers (ECCMODE, ECC1STSEN, and ECCOAD) to disable writing */
R_BSP_RegisterProtectDisable (regs_to_unprotect);
```

## 6. project setup

This section explains how to add r\_bsp to a project.

## 6.1 How to add the BSP

This module must be added for each project in which it is used. Renesas recommends using the Smart Configurator.

(1) Adding the BSP using the Smart Configurator on e2 studio
Use the Smart Configurator on e2 studio to automatically add BSP to user projects. For details, refer to
the RISC-V MCU Smart Configurator User's Guide: e2 studio (R20AN0730).

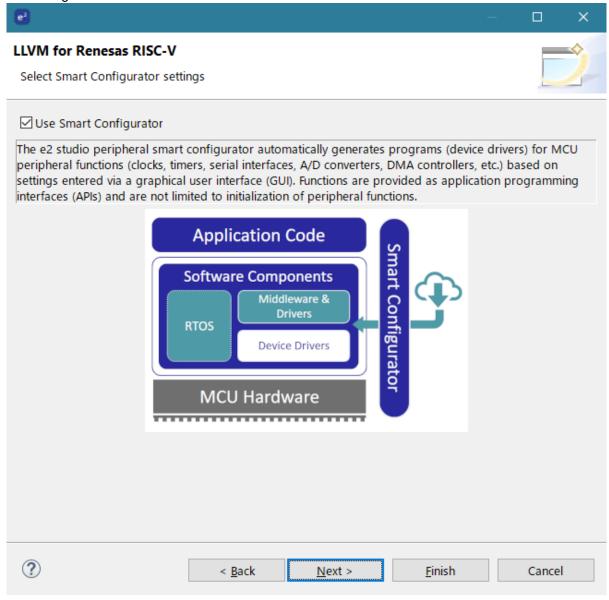
## 6.2 Adding the BSP to a Project in e<sup>2</sup> studio

How to add the BSP to a project in e<sup>2</sup> studio is described below.

## 6.2.1 Adding the BSP Using Smart Configurator in e<sup>2</sup> studio

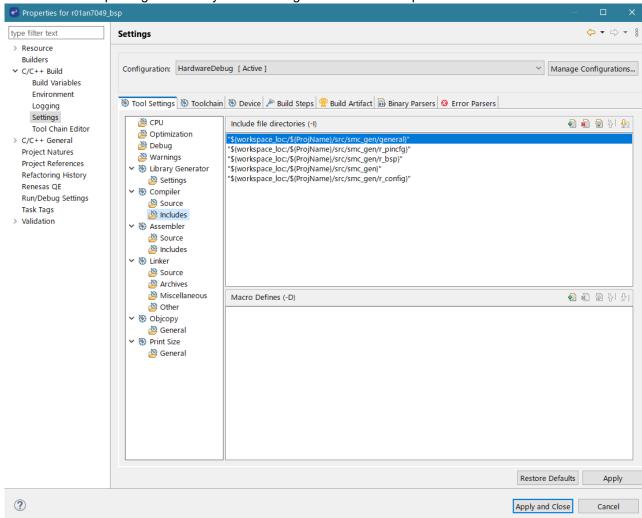
This explanation uses e<sup>2</sup> studio (2024-01).

Create a new project in e<sup>2</sup> studio.
 When creating your project, check the box next to "Use Smart Configurator" to launch Smart Configurator.



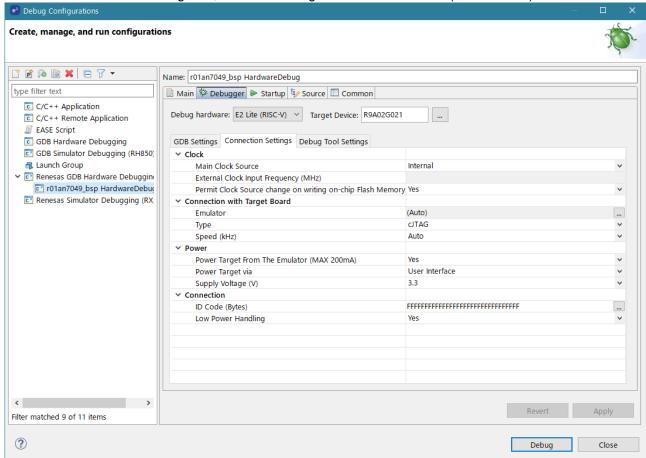
- 2. Follow the procedure described in 6.1, How to add the BSP, to add the BSP to your project in e² studio.
- 3. Right-click the project and click "Properties."
- 4. On the Tool Settings tab, select Compiler → Includes.

5. BSP include paths generated by Smart Configurator have been specified.



- 8. Right-click the project and click "Build Project."
- 9. Right-click the project and click "Debug" → "Configure Debugger."
- 10. Click "Renesas GDB Hardware Debugging" → "Project Name Hardware Debug."
- 11. On the Debugger tab, set "Debug hardware:" to "E2 Lite (RISC-V)."

13. On the Connection Settings tab, set "Power Target From The Emulator (MAX 200mA)" to "Yes."



## 7. Appendix

# 7.1 Confirmed Operating Environment

The environment in which the operation of the module has been confirmed is shown below.

Table 7.1 Confirmed Operating Environment (Rev. 1.00)

Item	Description
Integrated development environment	Renesas Electronics e <sup>2</sup> studio (2024-01.1)
C compiler	LLVM for RISC-V 17.0.2.202401
Module revision	Rev.1.00
Board used	FPB-R9A02G021 WS
	(Product type: RTK9FPG021S000W0BJ)

# **Revision History**

		Description	
Rev.	Date	Page	Summary
1.00	Mar.18.24	_	Initial release

# General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between  $V_{IL}$  (Max.) and  $V_{IH}$  (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not quaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

#### **Notice**

- 1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
- 2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
- 3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others
- 4. You shall be responsible for determining what licenses are required from any third parties, and obtaining such licenses for the lawful import, export, manufacture, sales, utilization, distribution or other disposal of any products incorporating Renesas Electronics products, if required.
- 5. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
- 6. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.
  - "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.
  - "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.

- 7. No semiconductor product is absolutely secure. Notwithstanding any security measures or features that may be implemented in Renesas Electronics hardware or software products, Renesas Electronics shall have absolutely no liability arising out of any vulnerability or security breach, including but not limited to any unauthorized access to or use of a Renesas Electronics product or a system that uses a Renesas Electronics product. RENESAS ELECTRONICS DOES NOT WARRANT OR GUARANTEE THAT RENESAS ELECTRONICS PRODUCTS, OR ANY SYSTEMS CREATED USING RENESAS ELECTRONICS PRODUCTS WILL BE INVULNERABLE OR FREE FROM CORRUPTION, ATTACK, VIRUSES, INTERFERENCE, HACKING, DATA LOSS OR THEFT, OR OTHER SECURITY INTRUSION ("Vulnerability Issues"). RENESAS ELECTRONICS DISCLAIMS ANY AND ALL RESPONSIBILITY OR LIABILITY ARISING FROM OR RELATED TO ANY VULNERABILITY ISSUES. FURTHERMORE, TO THE EXTENT PERMITTED BY APPLICABLE LAW, RENESAS ELECTRONICS DISCLAIMS ANY AND ALL WARRANTIES, EXPRESS OR IMPLIED, WITH RESPECT TO THIS DOCUMENT AND ANY RELATED OR ACCOMPANYING SOFTWARE OR HARDWARE, INCLUDING BUT NOT LIMITED TO THE IMPLIED WARRANTIES OF MERCHANTABILITY, OR FITNESS FOR A PARTICULAR PURPOSE.
- 8. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
- 9. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
- 10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
- 11. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
- 12. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
- 13. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
- 14. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.
- (Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.
- (Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.5.0-1 October 2020)

### **Corporate Headquarters**

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

## **Trademarks**

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

## **Contact information**

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit: <a href="https://www.renesas.com/contact/">www.renesas.com/contact/</a>.